PCN Number:	20190214001.0		PCN Date:	February 19, 2019	
Title:	Datasheet for LMX2572				
Customer Contact:	PCN Manager			**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

LMX2572
SNAS740B – OCTOBER 2017 – REVISED JANUARY 2019

Changes from Revision A (October 2017) to Revision B   **Page**

- Changed RampDir pin description from: …ramp size selection… to: …ramp segment selection… 4
- Changed RFoutAM pin description from: High impedance… to: Low impedance… 4
- Changed RFoutAP pin description from: High impedance… to: Low impedance… 4
- Changed RFoutBM pin description from: High impedance… to: Low impedance… 4
- Changed RFoutBP pin description from: High impedance… to: Low impedance… 4
- Changed VbiasVCO pin decoupling capacitor requirement 5
- Changed VbiasVCO2 pin decoupling capacitor requirement 5
- Changed VccMASH pin decoupling capacitor requirement 5
- Changed VccVCO pin decoupling capacitor requirement 5
- Changed VccVCO2 pin decoupling capacitor requirement 5
- Changed VregVCO pin decoupling capacitor requirement 5
- Added Vtune pin shunt capacitor requirement 5
- Changed V_{OH} and V_{OL} data in Electrical Characteristics 8
- Changed SCK to CSB low time symbol 8
- Changed Figure 28 13
- Added charge pump gain table 16
- Deleted sentence 'When the device comes out of the powered down state, either by resuming the POWERDOWN bit to zero or by pulling back CE pin HIGH (if it was powered down by CE pin), it is required that register R0 with FCAL_EN = 1 be programmed again to re-calibrate the device.' from the *Powerdown* section 18
- Added sentence 'The wake-up time for the device to come out of the powered state is adjustable.' to the *Powerdown* section 18
- Changed *Programming Sequence* step from: Wait 100 µs… to: Wait 500 µs… 21
- Changed R6 initial programming from: No to: Depends 21
- Changed R52 initial programming from: No to: Yes 22

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMX2572	SNAS740A	SNAS740B

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/LMX2572

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMX2572RHAR	LMX2572RHAT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com